



LEGEND:

- A. #14 AWG (19/27) SILVER PLATED COPPER $\phi.071$
- B. SEMICON EP (.020 THK) TO $\phi.111 \pm.005$
- C. INSULATING EP TO $\phi.306 \pm.010$
- D. SEMICON EP (.015 THK) TO $\phi.336 \pm.010$
- E. #30 AWG T.C. BRAID 95% COVERAGE TO $\phi.381 \pm.015$
- F. .003 IN MYLAR TAPES 1/2 LAPPED 2 LAYERS $\phi.405$
- G. #30 AWG T.C. BRAID 90% COVERAGE TO $\phi.450 \pm.015$
- H. SEMICON EP (.020 THK) TO $\phi.505$ OVER SEMI CONDUCTIVE TAPE
- I. INSULATING EP TO $\phi.755 \pm.015$
- J. SEMICON EP (.015 THK) TO $\phi.785$
- K. #34 AWG T.C. BRAID 90% COVERAGE TO $\phi.833 \pm.020$
- L. JACKET: POLYURETHANE OVER .002 MYLAR SEPARATOR, .085 WALL NOMINAL (.06 WALL MIN) TO $1.000 \pm.025$

THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF DIELECTRIC SCIENCES, INC. NO DIMENSIONS ARE IN INCHES SHALL NOT BE REPRODUCED OR COPIED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS WITHOUT PERMISSION.		UNLESS OTHERWISE SPECIFIED	DATE DRAWN	DIELECTRIC SCIENCES, INC.		
		DECIMALS	05NOV98			
INTERPRET DRAWING IN ACCORDANCE WITH ANSI Y14.5M-1982		FRAC	DRAWN BY	QUADRAXIAL CABLE		
		ANGLES	GPLAMBERT			
		.XX ± .01 ±	APPROVED	FSCM NO. 50509 SIZE A DRAWING NO. 2241 REV 1		
		.XXX ± .005 ±	MATERIAL			
		CONCENTRICITY .005 TIR	FINISH	SCALE _____ SHEET _____		
		REMOVE BURRS & SHARP EDGES				
NEXT ASSY	USED ON	ALL MACHINE SURFACES ✓25	NG			
APPLICATION DO NOT SCALE THIS DRAWING						